# ANNEX 10 Standardization work at ISO/IEC- Working Groups and Experts registered

# 1. IEC TC 40 - Capacitors and resistors for electronic equipment (P Member)

## **Structure:**

WG	Title	Experts Nominated from India
WG 36	Packaging of components for automatic handling	Mr Mandar Pramod Sinnarkar
WG 40		Mr Bipin Jambholkar Mr Vidyadhar K Mahajan Mr Mandar Pramod Sinnarkar
WG 41		Mr Vidyadhar K Mahajan Mr Mandar Pramod Sinnarkar (Convenor)
WG 43	Non-linear Resistors	

# 2. IEC TC 91 - Electronics assembly technology (P Member)

#### **Structure:**

WG	Title	<b>Experts Nominated from India</b>
WG 1	Requirements for electronic components	Mr Mandar Pramod Sinnarkar
WG 2	Requirements for electronics assemblies	Mr Mandar Pramod Sinnarkar
WG 3	Measuring and test methods for electronics	Mr Mandar Pramod Sinnarkar
WUJ	assemblies	
WG 4	Printed boards and materials	Mr Mandar Pramod Sinnarkar
WG 5	Vocabulary	
WG 6	Device Embedding assembly technology	Mr Mandar Pramod Sinnarkar
WG 10	Measuring and test methods for circuit boards	Mr Mandar Pramod Sinnarkar
	and circuit board materials	
WG 12	Design methodology and data transfer of	
	circuit boards and circuit board assemblies	
WG 13	Design Automation: Component, Circuit and	
	System Description Language	
WG 15	Design Automation: Testing of	
	Electrotechnical Products	

# 3. IEC TC 47 - Semiconductor devices (O Member)

#### **Structure:**

WG	Title	Experts Nominated from India
WG 1	Terminology	Nil
WG 2	Semiconductor Device Test Methods and	Nil
	Guidelines - Mechanical, Climatic and Storage	
WG 5	Wafer Level Reliability for semiconductor	Nil
	devices	
WG 6	Incubating Working Group	Nil
WG 7	Semiconductor devices for energy conversion	Nil
	and transfer	
WG 8	Wide bandgap technologies – Power electronic	Nil
	conversion	

## 4. IEC SC 47A - Integrated circuits (O Member)

## **Structure:**

WG	Title	Experts Nominated from India
WG 2	Modelling of integrated circuits for behavioural	Nil
	simulation	
WG 7	Heterogeneous ICs	Nil
WG 9	Test procedures and measurement methods for	Nil
	EMC in integrated circuits	

## 5. IEC SC 47D - Semiconductor devices packaging (Not a Member)

## **Structure:**

WG	Title	<b>Experts Nominated from India</b>
WG 1	Package outlines	Nil
WG 2	Terms, definitions, measuring methods and	Nil
	related requirement for semiconductor devices	
	packaging	

# 6. IEC SC 47E - Discrete semiconductor devices (Not a Member)

## **Structure:**

WG	Title	Experts Nominated from India
WG 1	Semiconductor sensors	Nil
WG 2	Microwave devices	Nil
WG 3	Power devices	Nil
WG 4	Optocouplers, photocoplers and solid state opto-relays	Nil
WG 8	Magnetic and capacitive couplers for basic and reinforced isolation	Nil
WG 9	Laser diodes, LEDs, PDs and APDs	Nil

# 7. IEC SC 47F - Micro-electromechanical systems (Not a Member)

## **Structure:**

WG	Title	Experts Nominated from India
WG 1	Terminologies and generic specification for	Nil
	micro-electromechanical systems	
WG 2	Characterizations and testing methods of	Nil
	materials and structures for	
	microelectromechanical systems	
WG 3	Micro-electromechanical devices and	Nil
	packaging	